## **Product/Process Change Notice (PCN)** Major change ☐ Minor change PCN #: PCN\_FeCBF\_20150507\_Capacity\_Increase ☐ Product Mark ☐ Date Code Product Affected: WE-CBF Packaging Effective Date: 01.09.2015 ○ Others Contact: Product Management Attachment: ☐ Yes ⊠ No Phone: +49 (0) 7942 - 945 5001 Samples: Fax: +49 (0) 7942 - 945 5179 E-mail: pcn.eisos@we-online.de **DESCRIPTION AND PURPOSE OF CHANGE:** In order to increase the production capability Würth Elektronik eiSos GmbH & Co. KG will implement another production line. Process approval is according to internal requirements released by the Quality Department and the Product Management Department. **DETAIL OF CHANGE:** 1. Neither electrical nor mechanical properties of the part will be changed. The production lines can be identified by the first three digits of the lot number. 2. Lot No. of already established production line: Lot number starting with 187 Country of Origin: Taiwan Lot No. of additional production line: Lot number starting with 241 Country of Origin: Taiwan

3. Affected part numbers:

Size	Part number
0805	742792034
	74279207
	74279209
	742792038
	742792012
	74279207R

Size	Part number	
1206	74279214	
1806	7427924	
	74279243	
	74279245	
1812	7427925	
	74279253	

## **RELIABILITY / QUALIFICATION SUMMARY:**

Please see the Reliability Overview as below. All Tests were passed

	Test	Qty	Reference	Test conditions		
1	High Temperature Exposure (Storage)	0/30	MIL-STD-202 Method 108	Preconditioning: 1 time lead-free Heat exposure Temperature: 125±3°C* Testing time: 500h Unpowered. Measurement at 24±2 hours after test conclusion.		
2	Moisture Resistance	0/30	MIL-STD-202 Method 106	Preconditioning: 1 time lead-free Heat exposure Time/Cycle = 24 h; Temperature: 65±2°C 500h, Humidity: 95%, Unpowered. Measurement at 24±2 hours after test conclusion.		
3	Operational Life	0/30	MIL-PRF-27	Preconditioning: 1 time lead-free Heat exposure Testing time: 1000h Temperature: Ambient Temp. 85±5°C* + rated current = 125°C* Measurement at 24±2 hours after test conclusion.		
4	Terminal Strength (SMD)	0/30	internal spec.	Preconditioning: Solder components on test board (lead-free) Apply an individual force for 60 seconds. Please refer the attached table in the description below.		
5	Vibration	0/30	MIL-STD-202 Method 204	Preconditioning: Solder components on test board (lead-free) 10g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8"X5" PCB, .031" thick, 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 15-2000 Hz.		
6	Five Time Reflow	0/30	J-STD-020D	Lead -free soldering profile: Peak temperature according to table 4.2 of the J-STD-020		
7	Solderability	0/30	JESD22-B102	For both Leaded & SMD. Electrical Test not required. Magnification 50X. Conditions: SMD: a) Method B, Steam Aging 4 hrs @ 98% r.H.@ 245°C		
8	Thermal Shock	0/30	MIL-STD-202 Method 107	Preconditioning: 1 time lead-free Heat exposure Temperature: -40°C/+125°C* Dwell time is 30 minutes. Cycles: 300 Transfer time max. 20s.		
9	Board Flex	0/30	AEC-Q200-005	Preconditioning : Solder components on test board (lead-free) Appendix 2 Note: 2mm (Min) Sample size: 30		
10	Low Temperature Storage Life	0/30	JESD22-A119	Preconditioning: 1 time lead-free Heat exposure Temperature: -55±3°C Testing time: 500h Measurement at 24±2 hours after test conclusion.		

Note: *Use max. or min. temperatures	according Würth Elektronik data shee	t (current version) 30 pcs of each DUT (Device Under Te	est)
DATA SHEET CHANGE:	☐ Yes	⊠ No	